

# IEEE-ICEV 2020<sup>®</sup>

## 2020 IEEE International Conference on Engineering Veracruz

Smart technologies under the triple helix model of innovation

Boca del Río, Veracruz, México – 26 to 29 October 2020

<https://www.uv.mx/ieee-icev/>

### CALL FOR PAPERS – Extended deadline!

On behalf of the Organizing Committee, we have the pleasure to invite you to submit your contributions to the 2020 IEEE International Conference on Engineering Veracruz (IEEE ICEV 2020<sup>®</sup>) (2020 IEEE Congreso Internacional de las Ingenierías Veracruz). The conference will be held in Boca del Río, Veracruz, México from 26 to 29 October 2020, organized by the Universidad Veracruzana (DGAAT-Dirección General del Área Académica Técnica, Vicerrectoría Veracruz, Centro de Investigación en Micro y Nanotecnología, and Facultades de Ingeniería) and the IEEE Student Branches and IEEE EDS Student Chapter with the support of IEEE Veracruz Section, Universidad Cristóbal Colón, Dirección General de Investigaciones UV and Consejo Veracruzano de Investigación Científica y Desarrollo Tecnológico (COVEICYDET).

IEEE ICEV 2020 is technically sponsored by IEEE. Accepted papers will be submitted for inclusion into IEEE Xplore. Authors from all over the world are invited to submit original and unpublished papers, which are not under review in any other conference. All papers will be peer reviewed by the technical program committee. Submitted papers must be written in English and should be in PDF format. Paper length must be between 4 and 8 pages.

The ISBN of the conference proceedings for IEEE Xplore is:

**978-1-7281-7474-7**

which will be published under the copyright of the IEEE.

### Submission Guidelines

All papers must be original and not simultaneously submitted to another journal or conference.

Papers must be prepared using the IEEE conference templates, available through the link:

<https://www.uv.mx/ieee-icev/submission-of-papers/>

All papers must be sent directly to the conference chair email: [jaimartinez@uv.mx](mailto:jaimartinez@uv.mx)

## Important information

On behalf of the Organizing Committee of the 2020 IEEE International Conference on Engineering Veracruz (IEEE ICEV2020<sup>®</sup>), we would like to communicate to the scientific and academic community that, taking into consideration the global health contingency that we have been suffering this year, which has caused problems for the continuity of research projects, difficulties for inter-institutional collaboration, and above all, causing great uncertainty regarding the production of articles, papers, and support for their dissemination at scientific and academic events:

1. It has been decided to extend the deadline until August 30 of this year, considering the request in this regard by numerous researchers, academics, and students. We also take the opportunity to thank and acknowledge their efforts to all those who have sent their work for review in a timely manner.
2. The organization of the 2020 IEEE International Conference on Engineering Veracruz (IEEE ICEV 2020<sup>®</sup>) event will be held in a virtual environment, in order to abide by sanitary regulations, avoiding any risks and allowing attendees to participate regardless of their geographical location, in order to expand the diffusion of the topics of interest solicited at the conference. Considering this situation, your participation in the remote conference for IEEE ICEV 2020<sup>®</sup> is highly encouraged, which will allow all participants to connect and take part in the sessions from your own computer(s). Thank you for your kind understanding.

Paper Submission Deadline:	August 30, 2020
Notification of acceptance:	September 15, 2020
Camera-ready due:	September 30, 2020
Registration and Payment Deadline for authors:	October 15, 2020
Registration Deadline:	October 26, 2020
Presentation of papers:	26 to 29 October 2020



-IEEE International Conference on Engineering Veracruz 2019

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## List of Topics

IEEE-ICEV 2020 will deal with smart technologies under the triple helix model of innovation, i.e. the combined efforts of academia, industry and government for sustainable development using intelligent devices and technologies.

Authors are invited to submit contributions including, but not limited to the following areas:

- Power Engineering
- Materials Science and Engineering
- Nanomedicine and Biomedical Engineering
- Mechanical Engineering
- Electrical Engineering
- Electronic Engineering
- Mechatronics Engineering
- Chemical Engineering
- Computational Engineering
- Energy Harvesting
- Micro and nanosystems
- Micro and nanotechnology
- Communication systems
- Devices and sensors
- MEMS & NEMS
- Application Specific Integrated Circuits (ASIC)
- Modelling and Simulation
- Internet of Things and Industry 4.0
- Electronic Instrumentation Engineering
- Signal Processing Engineering
- Physics and Optical Engineering
- Educational Innovation with Information and Communication Technologies
- Information Technologies in Organizations
- Information Technology Management
- Research, Innovation and Development in Organizations